

Description

The AP20P04D uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = -40V I_{D} = -20A$

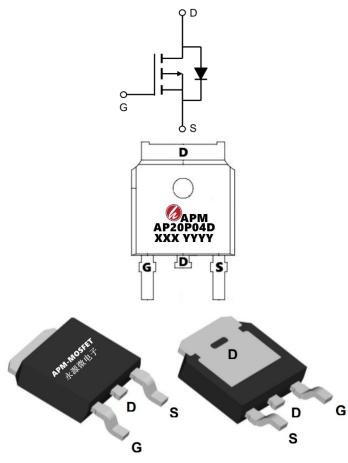
 $R_{DS(ON)} < 40 \text{m}\Omega$ @ V_{GS} =-10V (Type: 30m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

| Product ID | Product ID Pack | | Qty(PCS) | |
|------------|-----------------|-------------------|----------|--|
| AP20P04D | TO-252-3L | AP20P04D XXX YYYY | 2500 | |

Absolute Maximum Ratings (T_c=25℃unless otherwise noted)

| Symbol | Parameter | Rating | Units |
|---|--|------------|-------|
| VDS | VDS Drain-Source Voltage | | V |
| VGS | Gate-Source Voltage | ±20 | V |
| I _D @T _C =25℃ | Continuous Drain Current, -V _{GS} @ -10V ¹ | -20 | А |
| I _D @T _C =100°C | Continuous Drain Current, -V _{GS} @ -10V ¹ | -18 | А |
| IDM | Pulsed Drain Current ² | -60 | А |
| EAS | Single Pulse Avalanche Energy ³ | 37 | mJ |
| IAS | Avalanche Current | -27.2 | А |
| P _D @T _C =25°C | Total Power Dissipation ⁴ | 31.3 | W |
| TSTG | Storage Temperature Range | -55 to 150 | °C |
| TJ | Operating Junction Temperature Range | -55 to 150 | °C |
| ReJA | Thermal Resistance Junction-Ambient ¹ | 62 | °C/W |
| R _θ JC Thermal Resistance Junction-Case ¹ | | 4 | °C/W |





Electrical Characteristics (T_J=25°C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Тур. | Max. | Unit |
|------------------------|--|--|-------|--------|------|------|
| BVDSS | Drain-Source Breakdown Voltage V _{GS} =0V , I _D =-250uA | | -40 | -46 | | V |
| △BVbss/△TJ | BV _{DSS} Temperature Coefficient Reference to 25 °C , I _D =-1mA | | | -0.012 | | V/°C |
| D | Static Ducin Source On Besistance? | V _{GS} =-10V , I _D =-18A | 30 40 | | 0 | |
| Rds(on) | Static Drain-Source On-Resistance ² | V _{GS} =-4.5V , I _D =-12A | | 45 | 60 | mΩ |
| V _G S(th) | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =-250uA | -1.0 | -1.6 | -2.5 | V |
| $\triangle V_{GS(th)}$ | V _{GS(th)} Temperature Coefficient | VGS-VDS , ID250UA | | 4.32 | | mV/℃ |
| Inco | Drain Source Leakage Current | V _{DS} =-32V , V _{GS} =0V , T _J =25°C | | | 1 | |
| Ipss | Drain-Source Leakage Current | V _{DS} =-32V , V _{GS} =0V , T _J =55℃ | | | 5 | uA |
| Igss | Gate-Source Leakage Current | V_{GS} =±20 V , V_{DS} =0 V | | | ±100 | nA |
| gfs | gfs Forward Transconductance V _{DS} =-5V , I _D =-18A | | | 12.6 | | S |
| R_g | Gate Resistance V _{DS} =0V , V _{GS} =0V , f=1MHz | | | 13 | | Ω |
| Q_g | Total Gate Charge (-4.5V) | | | 9 | | nC |
| Qgs | Gate-Source Charge | V_{DS} =-20V , V_{GS} =-4.5V , I_{D} =- | | 2.54 | | |
| Qgd | Gate-Drain Charge | 127 | | 3.1 | | |
| Td(on) | Turn-On Delay Time | | | 19.2 | | |
| Tr | Rise Time | V_{DD} =-15V, V_{GS} =-10V , R_{G} =3.3 Ω , | | 12.8 | | ns |
| Td(off) | Turn-Off Delay Time | I _D =-1A | | 48.6 | | |
| Tf | Fall Time | 10171 | | 4.6 | | |
| Ciss | Input Capacitance | | | 1004 | | pF |
| Coss | Output Capacitance | V _{DS} =-15V , V _{GS} =0V , f=1MHz | | 108 | | |
| Crss | Reverse Transfer Capacitance | | | 80 | | |
| ls | Continuous Source Current ^{1,5} | V _G =V _D =0V , Force Current | | | -23 | Α |
| lsм | Pulsed Source Current ^{2,5} | VG-VD-OV, I OICE CUITEIIL | | | -46 | Α |
| VsD | Diode Forward Voltage ² V _{GS} =0V , I _S =-1A , T _J =25℃ | | | | -1 | V |

Note:

- 1. The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2_{\times} The data tested by pulsed , pulse width $\leqq 300 us$, duty cycle $\leqq 2\%$
- 3. The EAS data shows Max. rating . The test condition is V DD =-25V,V GS =-10V,L=0.1mH,I AS =-27.2A
- $4 \, {}^{\backprime}$ The power dissipation is limited by $150 \, {}^{\backprime}\!\!\!{}^{\backprime}$ junction temperature
- 5 The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.



Typical Characteristics

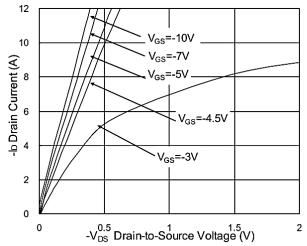


Fig.1 Typical Output Characteristics

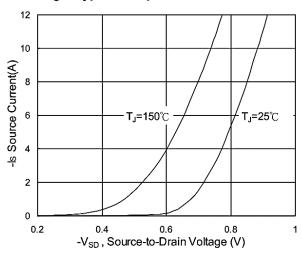


Fig.3 Forward Characteristics of Reverse

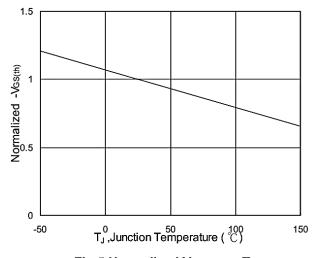


Fig.5 Normalized $V_{\text{GS(th)}}$ v.s T_{J}

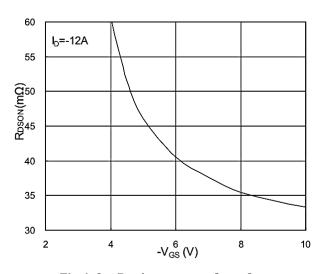


Fig.2 On-Resistance v.s Gate-Source

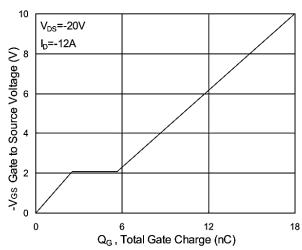


Fig.4 Gate-Charge Characteristics

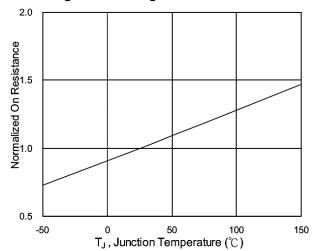


Fig.6 Normalized RDSON v.s TJ





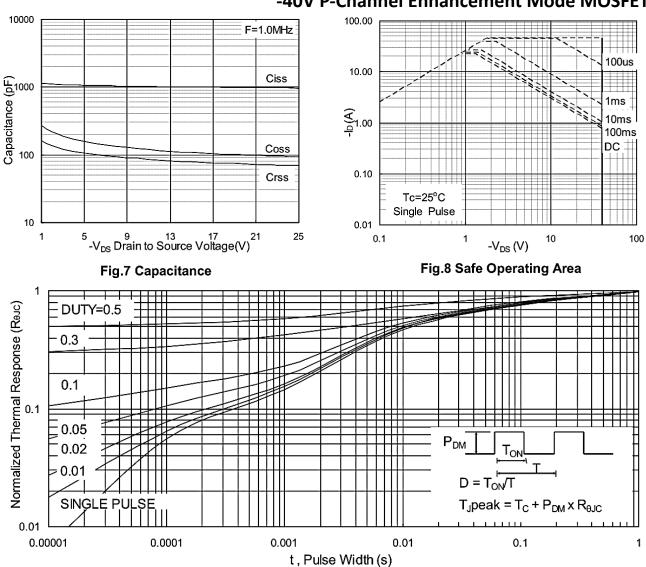


Fig.9 Normalized Maximum Transient Thermal Impedance

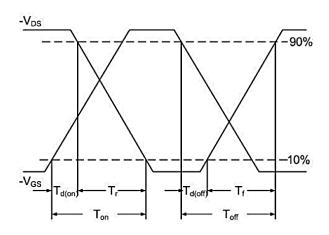


Fig.10 Switching Time Waveform

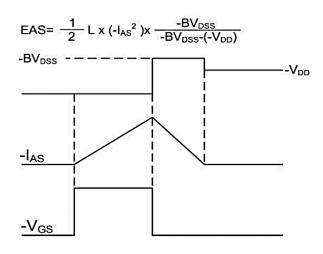
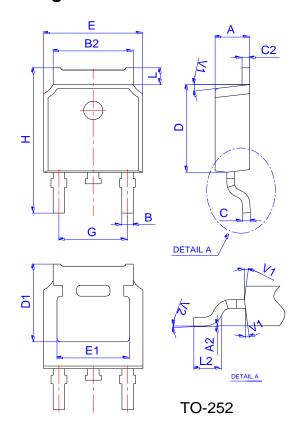


Fig.11 Unclamped Inductive Waveform

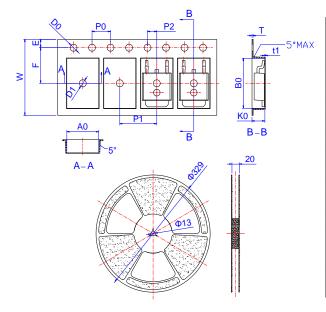


Package Mechanical Data:TO-252-3L



| Dimensions | | | | | | | |
|------------|-------------|---------|-------|--------|----------|-------|--|
| Ref. | Millimeters | | | Inches | | | |
| | Min. | Тур. | Max. | Min. | Тур. | Max. | |
| Α | 2.10 | | 2.50 | 0.083 | | 0.098 | |
| A2 | 0 | | 0.10 | 0 | | 0.004 | |
| В | 0.66 | | 0.86 | 0.026 | | 0.034 | |
| B2 | 5.18 | | 5.48 | 0.202 | | 0.216 | |
| С | 0.40 | | 0.60 | 0.016 | | 0.024 | |
| C2 | 0.44 | | 0.58 | 0.017 | | 0.023 | |
| D | 5.90 | | 6.30 | 0.232 | | 0.248 | |
| D1 | | 5.30REF | | | 0.209REF | | |
| E | 6.40 | | 6.80 | 0.252 | | 0.268 | |
| E1 | 4.63 | | | 0.182 | | | |
| G | 4.47 | | 4.67 | 0.176 | | 0.184 | |
| Н | 9.50 | | 10.70 | 0.374 | | 0.421 | |
| L | 1.09 | | 1.21 | 0.043 | | 0.048 | |
| L2 | 1.35 | | 1.65 | 0.053 | | 0.065 | |
| V1 | | 7° | | | 7° | | |
| V2 | 0° | | 6° | 0° | | 6° | |

Reel Spectification-TO-252



| | Dimensions | | | | | | |
|------|-------------|-------|-------|--------|-------|-------|--|
| Ref. | Millimeters | | | Inches | | | |
| | Min. | Тур. | Max. | Min. | Тур. | Max. | |
| W | 15.90 | 16.00 | 16.10 | 0.626 | 0.630 | 0.634 | |
| E | 1.65 | 1.75 | 1.85 | 0.065 | 0.069 | 0.073 | |
| F | 7.40 | 7.50 | 7.60 | 0.291 | 0.295 | 0.299 | |
| D0 | 1.40 | 1.50 | 1.60 | 0.055 | 0.059 | 0.063 | |
| D1 | 1.40 | 1.50 | 1.60 | 0.055 | 0.059 | 0.063 | |
| P0 | 3.90 | 4.00 | 4.10 | 0.154 | 0.157 | 0.161 | |
| P1 | 7.90 | 8.00 | 8.10 | 0.311 | 0.315 | 0.319 | |
| P2 | 1.90 | 2.00 | 2.10 | 0.075 | 0.079 | 0.083 | |
| A0 | 6.85 | 6.90 | 7.00 | 0.270 | 0.271 | 0.276 | |
| В0 | 10.45 | 10.50 | 10.60 | 0.411 | 0.413 | 0.417 | |
| K0 | 2.68 | 2.78 | 2.88 | 0.105 | 0.109 | 0.113 | |
| Т | 0.24 | | 0.27 | 0.009 | | 0.011 | |
| t1 | 0.10 | | | 0.004 | | | |
| 10P0 | 39.80 | 40.00 | 40.20 | 1.567 | 1.575 | 1.583 | |



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|---------|-----------|-----------------|
| Rve1.0 | 2021/1/10 | Initial release |

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